



BL-M8800DS7-40L

**802.11ax 287Mbps WLAN + BLE v5.4
SDIO/USB Module Specification**

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(Top View)



(Bottom View)

Module Name: BL-M8800DS7-40L	
Module Type: 802.11a/b/g/n/ac/ax 287Mbps WLAN +BLE v5.4 SDIO/USB Module	
Revision: V1.0	
Customer Approval:	
Company:	
Title:	
Signature:	Date:
LB-link Approval:	
Title:	
Signature:	Date:

Revision History

Revision	Summary	Release Date	Revised By
0.1	Initial release	2025-07-09	Zjh
1.0	Official release	2025-07-15	Zjh

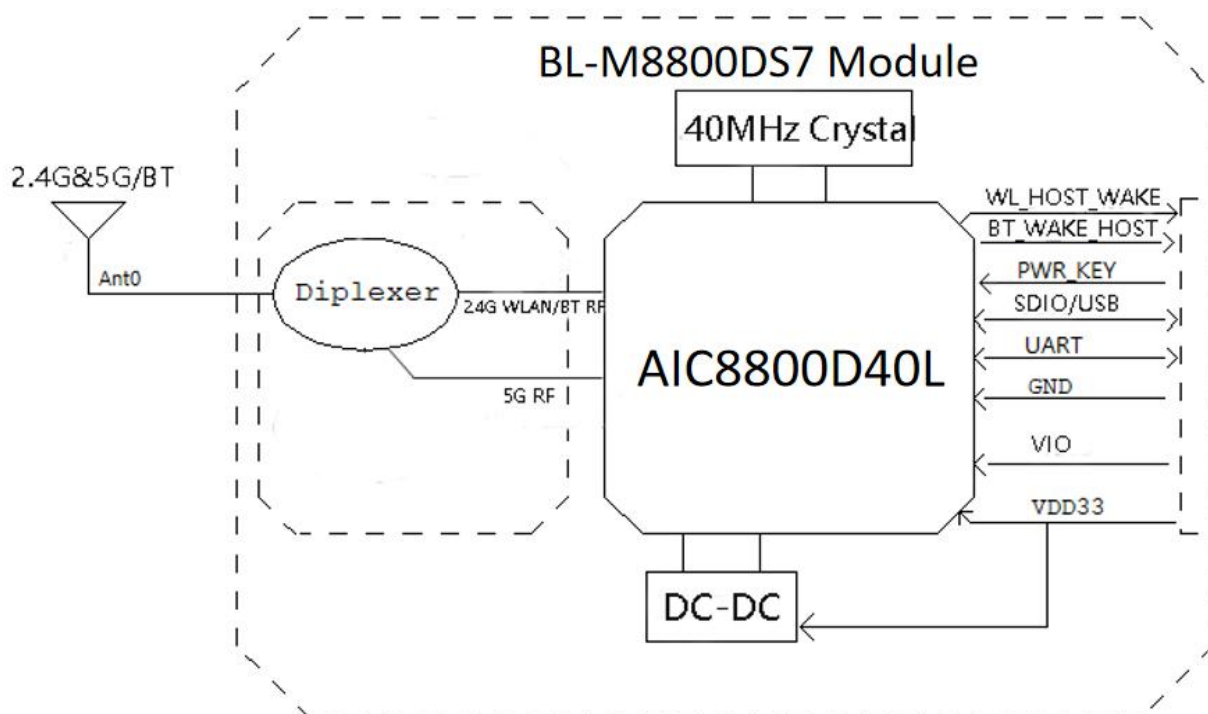
1. Introduction

BL-M8800DS7-40L is a highly integrated Dual-band WLAN + Bluetooth Combo module. It combines a 1T1R Dual-band WLAN subsystem and a Bluetooth v5.4 subsystem. This module compatible IEEE 802.11 a/b/g/n/ac/ax standard and provides the maximum PHY rate up to 287Mbps, offering feature-rich wireless connectivity at high standards, and delivering reliable, cost-effective, high throughput from an extended distance.

1.1 Features

- Operating Frequencies: 2.4~2.4835GHz or 5.15~5.85GHz
- Wireless PHY rate can reach up to 287Mbps with 20/40MHz bandwidth
- Host Interfaces are SDIO 3.0 or USB2.0 (Two interfaces cannot be used simultaneously)
- Support STA, AP, WLAN Direct modes concurrently
- Support BT Low Energy mode only

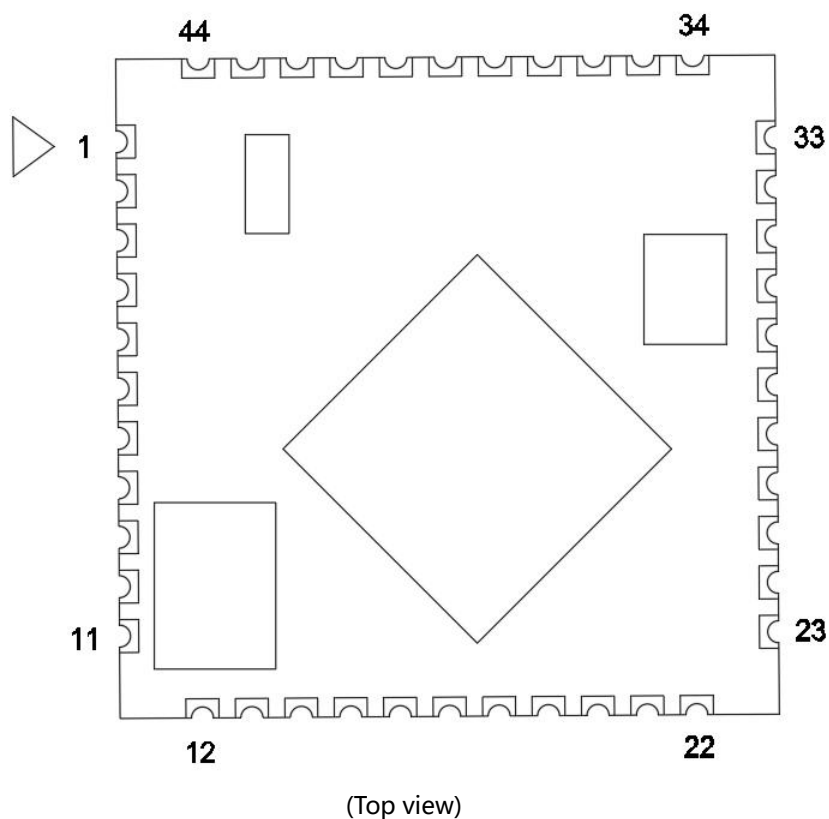
1.2 Block Diagram



1.3 General Specifications

Module Name	BL-M8800DS7-40L
Chipset	AIC8800D40L
WLAN Standards	IEEE802.11a/b/g/n/ac/ax
BT Specification	Bluetooth Core Specification v5.4/4.2
Host Interface	SDIO for WLAN & UART for Bluetooth or USB for WLAN + Bluetooth
Antenna	Connect to the external antenna through half hole pad
Dimension	12.0*12.0*1.8mm (L*W*H)
Power Supply	3.3V±0.2V main power supply @600mA (Max) 3.3V±0.2V or 1.8V±0.1V I/O power supply
Operation Temperature	-20°C to +70°C
Operation Humidity	10% to 95% RH (Non-Condensing)

2. Pin Assignments



2.1 Pin Definition

No	Pin Name	Type	I/O Level	Module Pin Description
1	GND	RF	/	RF Ground connections
2	ANT0	RF	/	RF Pad for 2.4G WLAN/5G WLAN/2.4G BT ANT
3	GND	RF	/	RF Ground connections
4	NC	/	/	NC (Reserved BT_RF PAD for BT ANT)
5	NC	/	/	NC
6	HOST_WAKE_BT	I/O	VIO	1.General Purpose Input / Output Pin GPIOB3 2.Host to wake-up this Bluetooth device input
7	BT_WAKE_HOST	I/O	VIO	1.General Purpose Input / Output Pin GPIOB2 2.Bluetooth device to wake-up Host output
8	NC	/	/	NC
9	VDD33	P	/	3.3V Main power supply
10	USB_DM	A I/O	/	USB 2.0 Device High Speed Interface differential pair
11	USB_DP	A I/O	/	USB 2.0 Device High Speed Interface differential pair
12	PWR_KEY	I	VDD33	Enable signal input, it can externally shut down the module by pulled low. When VDD33 and VIO are ready, PWR_KEY goes to high level exceeds 1.1V and lasts for 6mS, the module starts up, then the level of PWR_KEY must be maintained at VDD33. (internal pull up to VDD33 by 47K and pull down to GND by 200K resistors)
13	WL_HOST_WAKE	I/O	VIO	1.General Purpose Input / Output Pin GPIOB1 2.WLAN device to wake-up Host output
14	SD_D2	I/O	VIO	SDIO data line
15	SD_D3	I/O	VIO	SDIO data line
16	SD_CMD	I/O	VIO	SDIO command line
17	SD_CLK	I	VIO	SDIO clock line
18	SD_D0	I/O	VIO	SDIO data line
19	SD_D1	I/O	VIO	SDIO data line
20	GND	P	/	Ground connections
21	NC	/	/	NC
22	VIO	P	/	1.8V or 3.3V power supply for digital inputs/outputs, power-up timing requires VIO's power on time $\geq$ VDD33's. (USB application is recommended to use 3.3V or 1.8V I/O; SDIO 3.0 application must use 1.8V I/O)
23	NC	/	/	NC

24	HOST_WAKE_WF	I/O	VIO	1.General Purpose Input / Output Pin GPIOB0 2. Host to wake-up this WLAN device input
25	PCM_DOUT	I/O	VIO	1.General Purpose Input / Output Pin GPIOA3 2. PCM serial data signal output
26	PCM_CLK	I/O	VIO	1.General Purpose Input / Output Pin GPIOA1 2. PCM clock signal
27	PCM_DIN	I/O	VIO	1.General Purpose Input / Output Pin GPIOA2 2. PCM serial data signal input
28	PCM_FSYNC	I/O	VIO	1.General Purpose Input / Output Pin GPIOA0 2. PCM frame sync signal
29	UART0_TX	O	VIO	High-Speed UART Data Out (Debug pin)
30	UART0_RX	I	VIO	High-Speed UART Data In (Debug pin)
31	GND	P	/	Ground connections
32	NC	/	/	NC
33	GND	P	/	Ground connections
34	NC	/	/	NC (Bluetooth is enabled by default, Customers can disable or enable BT functionality by software)
35	NC	/	/	NC
36	GND	P	/	Ground connections
37	NC	/	/	NC
38	NC	/	/	NC
39	NC	/	/	NC
40	NC	/	/	NC
41	UART1_RTS	O	VIO	Bluetooth UART interface RTS
42	UART1_TX	O	VIO	Bluetooth UART interface TX
43	UART1_RX	I	VIO	Bluetooth UART interface RX
44	UART1_CTS	I	VIO	Bluetooth UART interface CTS

P: Power or Ground; I/O: In/Output; I: Input; O :Output; A I/O: Analog In/Output;
 AI: Analog Input; AO: Analog Output; RF: Analog RF Port or RF Ground

3. Electrical and Thermal Specifications

3.1 Recommended Operating Conditions

Parameters	Min	Typ	Max	Units
Ambient Operating Temperature	-20	25	70	°C

External Antenna VSWR			1.7	2.1	/
Supply Voltage	VDD33	3.1	3.3	3.5	V
	VIO_3.3V	3.1	3.3	3.5	V
	VIO_1.8V	1.7	1.8	1.9	V

3.2 DC Electrical Specification

Symbol	DESCRIPTION	Min	Typ	Max	Units
VIL	CMOS Low Level Input Voltage	0	--	0.3*VIO	V
VIH	CMOS High Level Input Voltage	0.7*VIO	--	VIO	V
VTH	CMOS Threshold Voltage	--	0.5*VIO	--	V

3.3 Current Consumption

Conditions : SDIO for networking test under Linux, VDD33=3.3V, VIO=1.8V; USB for RF test under Windows, VDD33=3.3V, VIO=3.3V; Ta:25°C;			
Use Case	VDD33 Current		
	Typ(I _{RMS})	Max(I _{Peak})	Units
WLAN & BT Unassociated (Linux SDIO Driver)	53	75	mA
2.4G WLAN throughput 200Mbps (Linux SDIO Driver)	185	385	mA
5G WLAN throughput 250Mbps (Linux SDIO Driver)	211	413	mA
2.4G 11b 1Mbps TX@18dBm (1TX RF test)	195	341	mA
2.4G 11g 6Mbps TX@18dBm (1TX RF test)	111	367	mA
2.4G 11n HT20_MCS0 TX@17dBm (1TX RF test)	176	365	mA
2.4G 11ax HE_SU 40M_MCS0 TX@15dBm (1TX RF test)	153	341	mA
2.4G 11ax HE_SU 40M_MCS11 TX@13dBm (1TX RF test)	64	301	mA
2.4G 11ax HE_SU 40M_MCS11 RX (1RX RF test)	45	53	mA
5G 11a 6Mbps TX@17dBm (1TX RF test)	166	425	mA
5G 11n HT20_MCS0 TX@17dBm (1TX RF test)	254	446	mA

5G VHT 80MHz MCS9 TX@14dBm (1TX RF test)	84	403	mA
5G 11ax HE_SU 80M_MCS11 TX@12dBm (1TX RF test)	86	368	mA
5G 11ax HE_SU 80M_MCS11 RX (1RX RF test)	55	79	mA
BT BR_1M TX@6dBm (BT RF test, WLAN disable)	37	46	mA
BT BR_1M RX Active (BT RF test, WLAN disable)	33	48	mA
BT EDR_3M TX@3dBm (BT RF test, WLAN disable)	36	45	mA
BT EDR_3M RX Active (BT RF test, WLAN disable)	45	49	mA
BT LE_1M TX@6dBm (BT RF test, WLAN disable)	32	43	mA

4. WLAN & Bluetooth RF Specifications

4.1 2.4G RF Specification

Conditions : USB for RF test under Windows, VDD33=3.3V, VIO=3.3V; Ta:25°C	
Features	Description
WLAN Standard	IEEE 802.11b/g/n/ax
Frequency Range	2.4~2.4835GHz (2.4GHz ISM Band)
Channels	Ch1~Ch13 (For 20MHz Channels)
Modulation	802.11b (DSSS): DBPSK, DQPSK, CCK; 802.11g (OFDM): BPSK, QPSK, 16QAM, 64QAM; 802.11n (OFDM): BPSK, QPSK, 16QAM, 64QAM; 802.11ax (OFDMA): BPSK, BPSK_DCM, QPSK, QPSK_DCM, QAM16, QAM16_DCM, QAM64, QAM256, QAM1024;
Data Rate	802.11b: 1, 2, 5.5, 11Mbps; 802.11g: 6, 9, 12, 18, 24, 36, 48, 54Mbps; 802.11n (HT20): MCS0~MCS7(1T1R_SISO) 6.5~72.2Mbps; 802.11n (HT40): MCS0~MCS7(1T1R_SISO) 13.5~150Mbps; 802.11ax (HE_MU,OFDMA 26~242RU): MCS0~MCS11(1T1R) 0.4~143.4Mbps; 802.11ax (HE_SU, non-OFDMA 20MHz): MCS0~MCS11(1T1R) 3.6~143.4Mbps; 802.11ax (HE_SU, non-OFDMA 40MHz): MCS0~MCS11(1T1R) 7.3~286.8Mbps;
Frequency Tolerance	≤ ±20ppm
2.4G Transmitter Specifications (TX power tolerance calibrated, customers can define the target TX power within recommended range by modifying configuration file of the driver software, Customers must define the TX power same or lower than recommended Target TX Power as below)	

TX Rate	Recommended Target TX Power (dBm)	TX Power Tolerance (dBm)	EVM (dB)
802.11b@1Mbps	18	±2	≤-10
802.11b@11Mbps	18	±2	≤-10
802.11g@6Mbps	18	±2	≤-10
802.11g@54Mbps	16	±2	≤-25
802.11n@HT20_MCS0	17	±2	≤-10
802.11n@HT20_MCS7	15	±2	≤-28
802.11n@HT40_MCS0	17	±2	≤-10
802.11n@HT40_MCS7	15	±2	≤-28
802.11ax@HE_SU 40M_MCS0	17	±2	≤-15
802.11ax@HE_SU 40M_MCS11	13	±2	≤-35

2.4G Receiver Specifications

RX Rate	Min Input Level (Typ dBm)	Max Input Level (Typ dBm)	PER
802.11b@1Mbps	-96	-5	< 8%
802.11b@11Mbps	-88	-5	< 8%
802.11g@6Mbps	-92	-5	< 10%
802.11g@54Mbps	-76	-5	< 10%
802.11n@HT20_MCS0	-92	-5	< 10%
802.11n@HT20_MCS7	-74	-5	< 10%
802.11n@HT40_MCS0	-89	-5	< 10%
802.11n@HT40_MCS7	-71	-5	< 10%
802.11ax@HE_SU 40M_MCS0	-89	-5	< 10%
802.11ax@HE_SU 40M_MCS11	-60	-5	< 10%

4.2 5G WLAN RF Specification

Conditions: USB for RF test under Windows, VDD33=3.3V, VIO=3.3V; Ta:25°C

Features	Description
WLAN Standard	IEEE 802.11a/n/ac/ax
Frequency Range	5.15~5.25GHz; 5.25~5.35GHz; 5.47~5.725GHz; 5.725~5.85GHz (5GHz ISM Band)
Channels	Ch36, Ch40, Ch44, Ch48; Ch52~Ch64; Ch100~Ch140; Ch149~Ch165(For 20MHz Channels)
Modulation	802.11a (OFDM): BPSK, QPSK, QAM16, QAM64;

	802.11n (OFDM): BPSK, QPSK, QAM16, QAM64; 802.11ac (OFDM): BPSK, QPSK, QAM16, QAM64, QAM256; 802.11ax (OFDMA): BPSK, BPSK_DCM, QPSK, QPSK_DCM, QAM16, QAM16_DCM, QAM64, QAM256, QAM1024;
Data Rate	802.11a: 6, 9, 12, 18, 24, 36, 48, 54Mbps; 802.11n (HT20): MCS0~MCS7 6.5~72.2Mbps; 802.11n (HT40): MCS0~MCS7 13.5~150Mbps; 802.11ac (VHT20): MCS0~MCS8(1T1R) 6.5~86.7Mbps; 802.11ac (VHT40): MCS0~MCS9(1T1R) 13.5~200Mbps; 802.11ax (HE_MU,OFDMA 26~242RU): MCS0~MCS11(1T1R) 0.4~143.4Mbps; 802.11ax (HE_SU, non-OFDMA 20MHz): MCS0~MCS11(1T1R) 3.6~143.4Mbps; 802.11ax (HE_SU, non-OFDMA 40MHz): MCS0~MCS11(1T1R) 7.3~286.8Mbps;
Frequency Tolerance	$\leq \pm 20\text{ppm}$

5G Transmitter Specifications (TX power tolerance calibrated, customers can define the target TX power within recommended range by modifying configuration file of the driver software, Customers must define the TX power same or lower than recommended Target TX Power as below)

TX Rate	Recommended Target TX Power (dBm)	TX Power Tolerance (dBm)	EVM (dB)
802.11a@6Mbps	17	± 2	≤ -10
802.11a@54Mbps	16	± 2	≤ -25
802.11n@HT20_MCS0	17	± 2	≤ -10
802.11n@HT20_MCS7	15	± 2	≤ -28
802.11n@HT40_MCS0	17	± 2	≤ -10
802.11n@HT40_MCS7	15	± 2	≤ -28
802.11ax@HE_SU 40M_MCS0	17	± 2	≤ -15
802.11ax@HE_SU 40M_MCS11	13	± 2	≤ -35

5G Receiver Specifications

RX Rate	Min Input Level (Typ dBm)	Max Input Level (Typ dBm)	PER
802.11a@6Mbps	-92	-5	< 10%
802.11a@54Mbps	-75	-5	< 10%
802.11n@HT20_MCS0	-91	-5	< 10%
802.11n@HT20_MCS7	-73	-5	< 10%

802.11n@HT40_MCS0	-88	-5	< 10%
802.11n@HT40_MCS7	-70	-5	< 10%
802.11ax@HE_SU 40M_MCS0	-88	-5	< 10%
802.11ax@HE_SU 40M_MCS11	-59	-5	< 10%

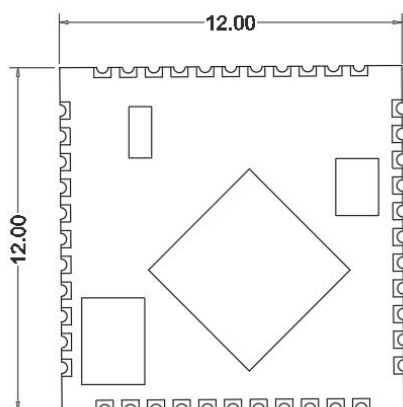
4.3 Bluetooth RF Specification

Conditions: USB for RF test under Windows, VDD33=3.3V, VIO=3.3V; Ta:25°C			
Features	Description		
Bluetooth Specification	Bluetooth Core Specification v5.4/4.2		
Frequency Range	2.4~2.4835GHz(2.4GHz ISM Band)		
Channels	Bluetooth Low Energy: Ch0~Ch39 (For 2MHz Channels);		
Power Classes	Bluetooth Low Energy: Class1.5;		
Data Rate & Modulation	LE_125Kbps: GFSK (Coded_S=8); LE_500Kbps: GFSK (Coded_S=2); LE_1Mbps: GFSK (Uncoded); LE_2Mbps: GFSK (Uncoded);		
Bluetooth Transmitter Specifications			
Items	Min (dBm)	Typ (dBm)	Max (dBm)
TX Power			
LE_125/500K	3	7	10
LE_1M	3	7	10
LE_2M	3	7	10
LE_1M Modulation Characteristics			
Δf1avg	225KHz	248.6KHz	275KHz
Δf2avg	185KHz	227KHz	275KHz
Δf2max	185KHz	202.2KHz	/
Δf2avg/Δf1avg	0.8	0.9	/
LE_2M Modulation Characteristics			
Δf1avg	450KHz	501.2KHz	550KHz
Δf2avg	370KHz	451KHz	550KHz

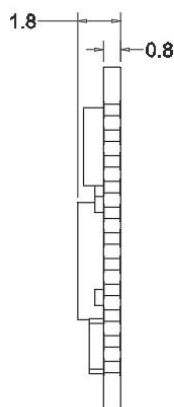
Δf2max	370KHz	469.8KHz	/	
Δf2avg/Δf1avg	0.8	0.9	/	
Bluetooth Receiver Specifications				
Items	Sensitivity		Maximum Input Level	
	Input Level (Typ. dBm)	PER	Input Level (Typ. dBm)	PER
LE_125/500K	-94	≤5%	-5dBm	≤5%
LE_1M	-91	≤5%	-5dBm	≤5%
LE_2M	-89	≤5%	-5dBm	≤5%

5. Mechanical Specifications

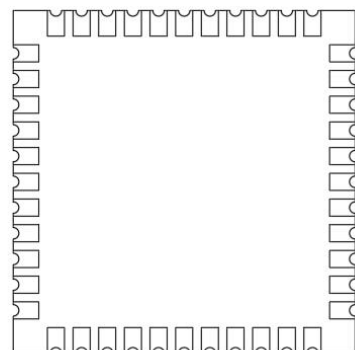
5.1 Module Outline Drawing (units:mm)



(Top View)

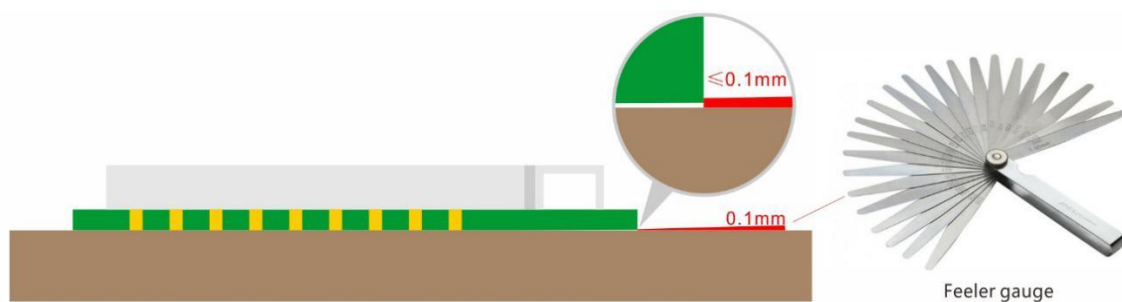


(Side View)



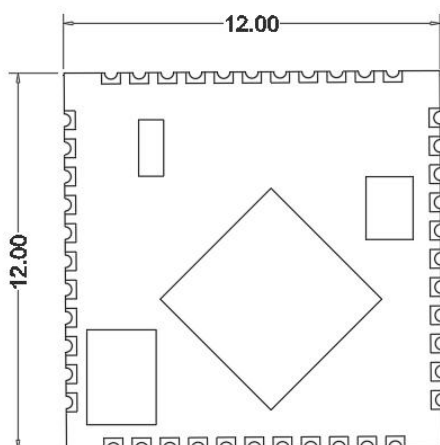
(Bottom View)

Module dimension: 12.0*12.0*1.8mm (L*W*H; Tolerance: $\pm 0.3\text{mm}_L/W$, $\pm 0.2\text{mm}_H$)

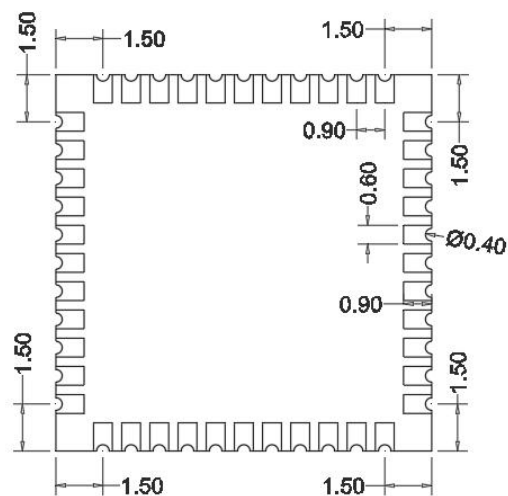


Module Bow and Twist: $\leq 0.1\text{mm}$

5.2 Mechanical Dimensions (units:mm)



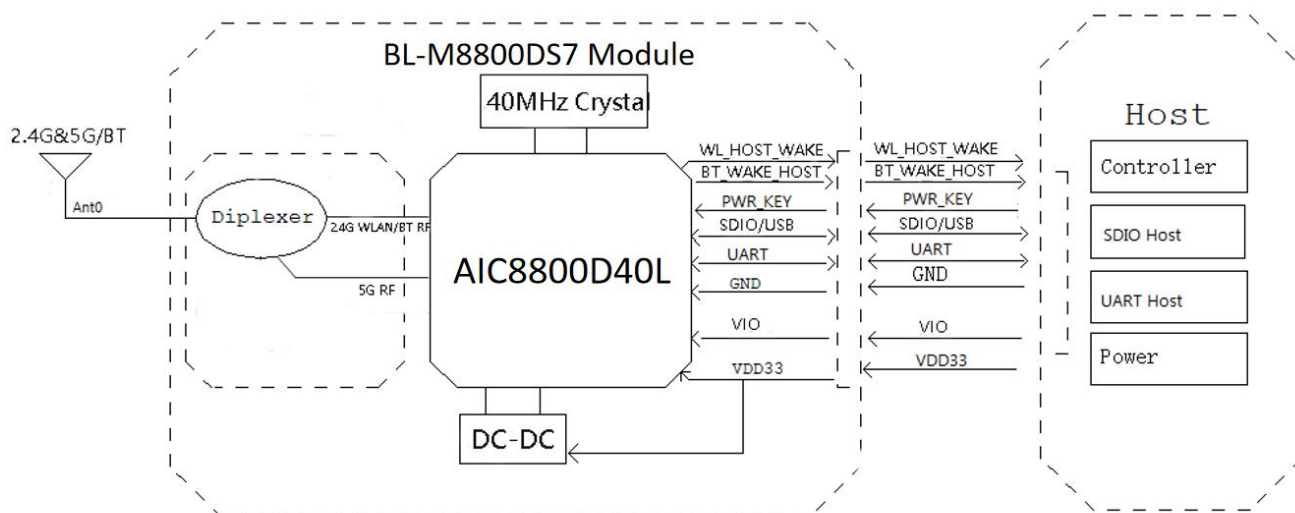
(Top View)



(Bottom View)

6. Application Information

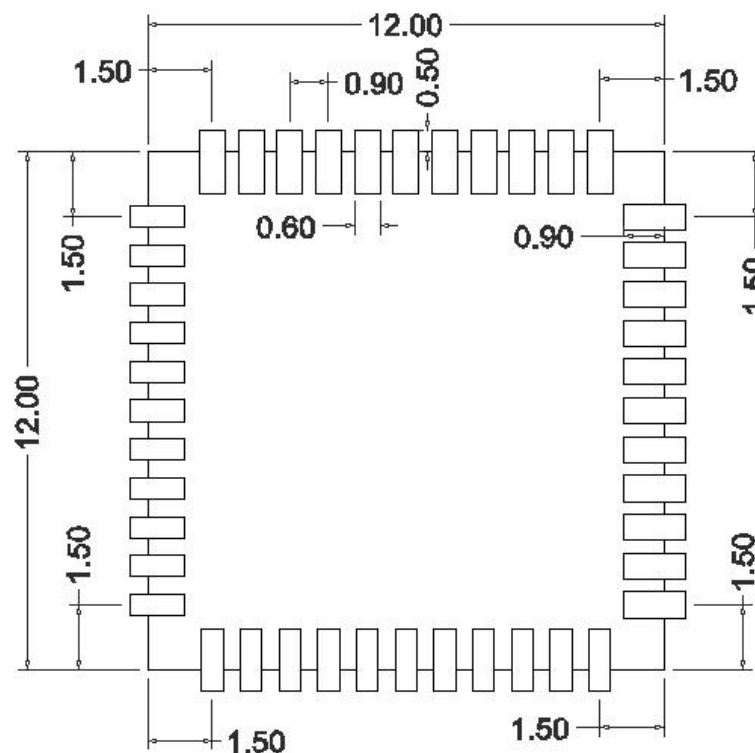
6.1 Typical Application Circuit



6.2 HW Application Note

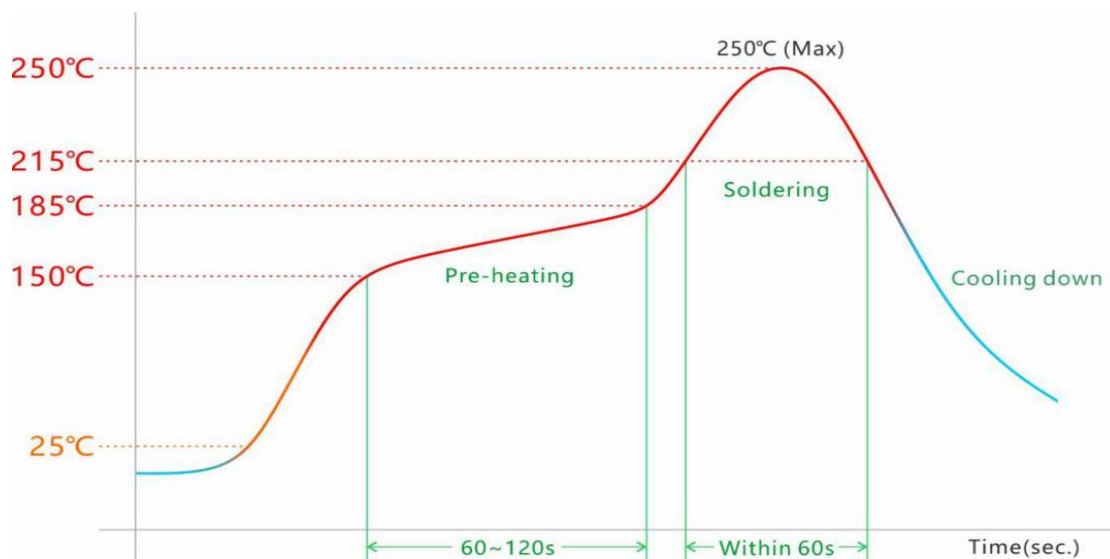
- a. On customer's motherboard, maintain a complete reference layer to reduce signal reflections and impedance changes.
- b. PCB traces of the RF path as short as possible, as far away from other signals as possible, avoid layer change, and should maintain continuous 50Ω characteristic impedance, structure of "Coated Coplanar Waveguide With Ground" with the advantages of impedance control and GND surrounding isolation interference may be an ideal choice.
- c. RF Pin and antenna PAD/RF connector PAD on customer's motherboard are significantly wider than PCB traces of the RF path, which will cause RF impedance discontinuity. To improve this problem, in addition to adjusting the local impedance of these PADs, a " π " circuit can be reserved near the antenna/RF connector which can match both RF path impedance and antenna impedance.
- d. PCB traces of the USB high-speed signal pair should maintain 90Ω differential impedance, structure of "Differential Coated Coplanar Waveguide With Ground" may be an ideal choice.
- e. PCB traces of SDIO3.0 high-speed bus as short as possible, as equal length as possible.
The SD_CLK signal needs series-source termination and maintain 50Ω characteristic impedance, GND surrounding isolation interference is recommended.
- f. For other SDIO signals, it is recommended to maintain $50\sim 65\Omega$ characteristic impedance and a spacing $>3W$ to avoid crosstalk.
- g. VDD33 main power supply: static ripple $<80\text{mV}$, $I_{\text{RMS}} \geq 500\text{mA}$ and $I_{\text{Peak}} \geq 600\text{mA}$, for fast transient response, a current mode buck converter is recommended.
Use $10\mu\text{F}$ and 100nF MLCC capacitors close to the module's VDD33 Pin for power input decoupling.
- h. VIO I/O power supply: Equivalent to the I/O level of customer's CPU platform, static ripple $<50\text{mV}$, $I_{\text{RMS}} < 50\text{mA}$, even simple LDO circuits can meet the requirements.
Use $2.2\mu\text{F}$ and 100nF MLCC capacitors close to the module's VIO Pin for power input decoupling.

6.3 Recommend PCB Layout Footprint(units:mm)



(Design Unit: mm)

6.4 Reflow Soldering Standard Conditions



Please use the reflow within 2 times.

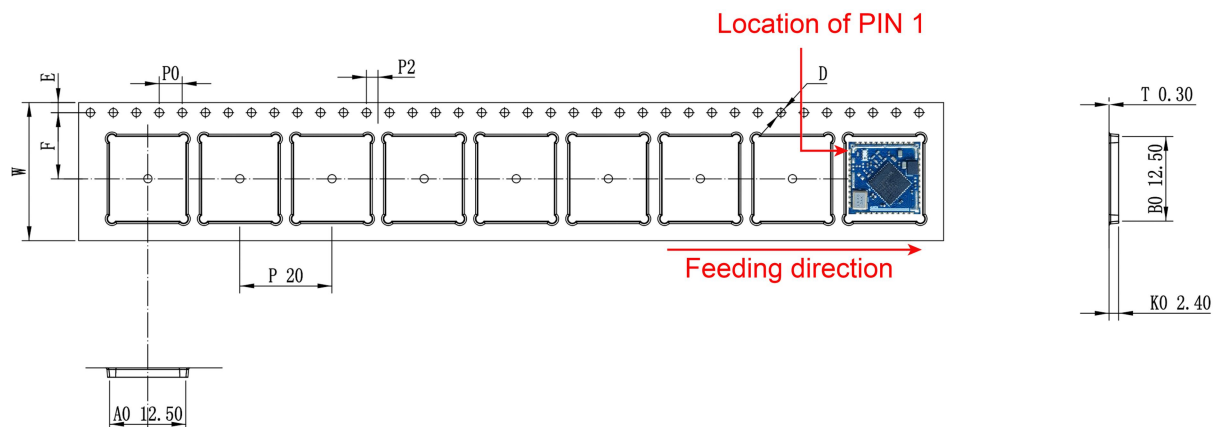
Set up the highest temperature within 250°C.

7. Key Components Of Module

No.	Parts	Specification	Manufacturer	Note
1	Chipset	AIC8800D40L	AIC Semiconductor (Shanghai) CO.,LTD	
2	PCB	BL-M8800DS7	SHEN ZHEN QILI ELECTRON CO.,LTD	
			Quzhou Sunlord Electronics Co.,LTD	
			ShenZhen Tie Fa Technology Limited	
3	Crystal	40MHz-3225	LUCKI CM ELECTRONICS CO.,LTD	
			Chengde oscillator Electronic Technology CO.,LTD	
			JinHua East Crystal Electronic CO.,LTD	
			HUBEI TKD CRYSTAL ELECTRONIC SCIENCE AND TECHNOLOGY CO.,LTD	
4	Diplexer	DIP1608	Shenzhen Sunlord Electronics Co.,LTD	
			Dongguan Hekang Electronics Co.,LTD	
			Shenzhen FTR Technologies CO., LTD	
			Walsin Technology Corporation	

8. Package and Storage Information

8.1 Package Dimensions



ITEM	W	A0	B0	K0	E	F	P	P0	P2	D	T
DIM	24.00±0.3	12.50±0.1	12.50±0.1	2.40±0.1	1.75±0.1	11.5±0.1	20.00±0.1	4.00±0.1	2.00±0.1	Ø1.5±0.1	0.30±0.05



Package specification:

- 1,000 modules per roll and 5,000 modules per box.
- Outer box size: 37.5*36*29cm.
- The diameter of the blue environment-friendly rubber plate is 13 inches, with a total thickness of 28mm (with a width of 24mm carrying belt).
- Put 1 package of dry agent (20g) and 1 humidity card in each anti-static vacuum bag.
- Each carton is packed with 5 boxes.

8.2 Storage Conditions

Absolute Maximum Ratings:

Storage temperature: -40°C to +85°C

Storage humidity: 10% to 95% RH (Non-Condensing)

Recommended Storage Conditions:

Storage temperature: 5°C to +40°C

Storage humidity: 20% to 90% RH

Please use this Module within 12month after vacuum-packaged.

The Module shall be stored without opening the packing.

After the packing opened, the Module shall be used within 72hours.

When the color of the humidity indicator in the packing changed, the Module shall be baked before soldering.

Baking condition: 60°C, 24hours, 1time.

ESD Sensitivity:

ESD Protection: 2KV(HBM, Maximum rating)

The Module is a static-sensitive electronic device.

Do not operate or store near strong electrostatic fields.

Take proper ESD precautions!



ESD CAUTION

Integration instructions for host product manufacturers according to KDB 996369
D03OEM Manual v01

2.2 List of applicable FCC rules

FCC Part 15 Subpart C 15.247 & 15.209 & 15.207.

2.3 Specific operational use conditions

The module can be used for mobile applications with a maximum 2.52dBi antenna. The host manufacturer installing this module into their product must ensure that the final composite product complies with the FCC requirements by a technical assessment or evaluation to the FCC rules, including the transmitter operation. The host manufacturer has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module. The end user manual shall include all required regulatory information/warning as shown in this manual.

2.4 Limited module procedures

The device is a Single module and complies with the requirement of FCC Part 15.212.

2.5 Trace antenna designs

Not applicable, The module has its own antenna, and does not need a host printed board micro strip trace antenna etc

2.6 RF exposure considerations

The device has been evaluated to meet general RF exposure requirement. The device can be used in portable exposure condition without restriction; and if RF exposure statement or module layout is changed, then the host product manufacturer required to take responsibility of the module through a change in FCC ID or new application. The FCC ID of the module cannot be used on the final product. In these circumstances, the host manufacturer will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

2.7 Antennas

Antenna Specification are as follows:

Type of antenna: PCB Antenna

Gain of antenna: 2.4GHz@ 2.52dBi Max. 5GHz@ 2.51dBi

This device is intended only for host manufacturers under the following conditions: The transmitter module may not be co-located with any other transmitter or antenna;

The module shall be only used with the internal antenna(s) that has been originally tested and certified with this module. The antenna must be either permanently attached or employ a "unique" antenna coupler

As long as the conditions above are met, further transmitter test will not be required

However, the host manufacturer is still responsible for testing their end-product for any additional compliance requirements required with this module installed (for example, digital device emissions, PC peripheral requirements, etc)

2.8 Label and compliance information

Host product manufacturers need to provide a physical or e-label stating " Contains FCC ID: FCC ID:2AL6KBL-M8800DS7 "with their finished product

2.9 Information on test modes and additional testing requirements

Host manufacturer must perform test of radiated & conducted emission and spurious emission, e.t.c according to the actual test modes for a stand-alone modular transmitter in a host, as well as for multiple simultaneously transmitting modules or other transmitters in a host product.

Only when all the test results of test modes comply with FCC requirements, then the end product can be sold legally.

2.10 Additional testing, Part 15 Subpart B disclaimer

The modular transmitter is only FCC authorized for FCC Part 15 Subpart C 15.247 &15209 &15.207 and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. If the grantee markets their product as being Part 15 Subpart B compliant (when it also contains unintentional-radiator digital circuit), then the grantee shall provide a notice stating that the final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed